

SANYO

No. ※ 4914

LC82141**Facsimile Controller****Preliminary****Overview**

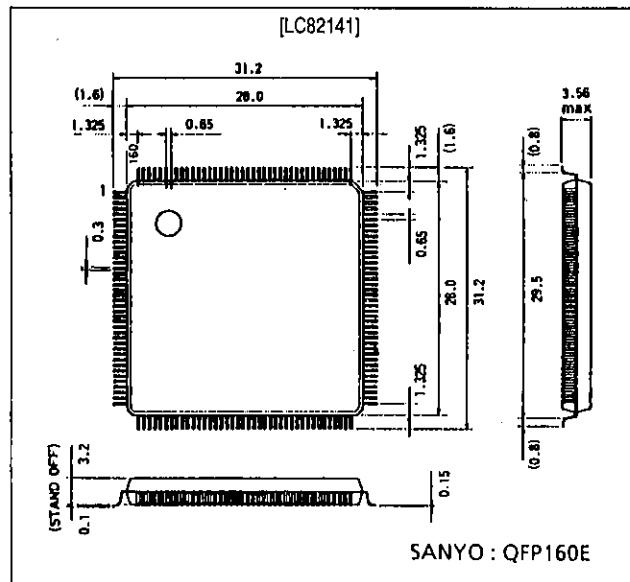
The LC82141 is a facsimile controller comprising a CPU, CPU peripheral circuits, image processor, dot change detector for image data compression and expansion, thermal print head interface, I/O ports and other facsimile functions on a single chip. It can be connected to a 9,600bps modem (LC8920, LC89201) or a 14,400bps modem (LC8921) and RAM, ROM, LCD controller and other circuits to form a high performance, low cost facsimile system.

Features

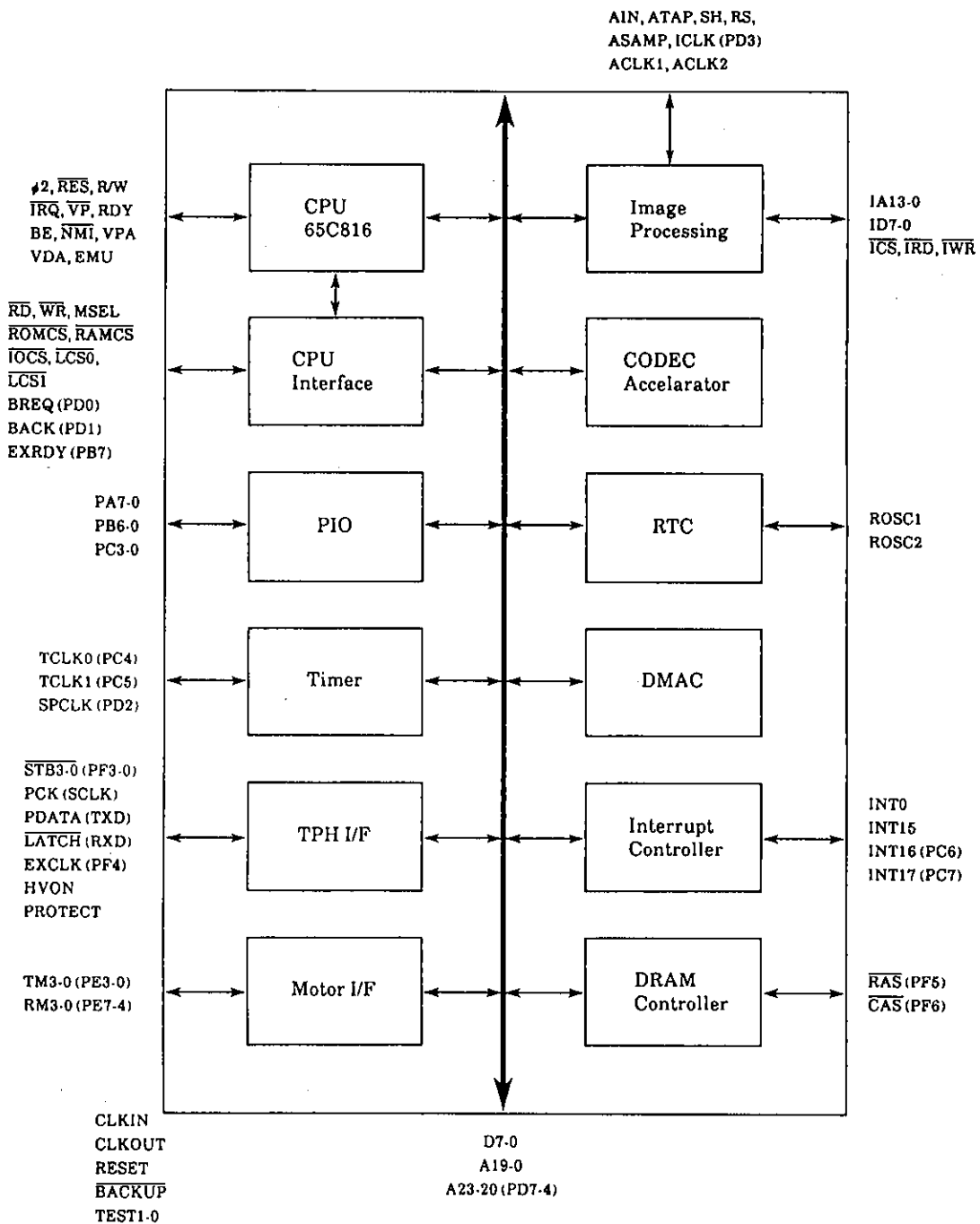
- High-speed 16-bit CPU (65C816), 8MHz cycle
- 16MB program space
- 3-channel DMA controller (2.6MB/s max.)
- 6-channel 16-bit timer
- 4096 pels/line image processing
- 64-gradation half-tone processing (dither method, error diffusion method)
- Shading correction for all pels
- AGC, 8-bit A/D converter
- Soft codec accelerator
- TPH interface (1,2,4 strobe divisions, latchless head)
- Transmit/receive stepping motor interface
- 32 I/O ports
- Single 5V supply
- CMOS process for low-power dissipation

Package Dimensions

unit: mm

3153-QFP160E

Block Diagram



Pin Functions

| Number | Name | IO ¹ | Description |
|--------|--------------------|-----------------|--------------------------------|
| 1 | V _{SS} | P | Ground connection pin |
| 2 | RD | O | Read signal from CPU |
| 3 | \overline{WR} | O | Write signal from CPU |
| 4 | \overline{ROMCS} | O | Program ROM chip select signal |
| 5 | \overline{RAMCS} | O | Work RAM chip select signal |

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| Number | Name | I/O ¹ | Description |
|--------|--------------------------|------------------|---------------------------------------|
| 6 | $\overline{\text{IOCS}}$ | O | External I/O chip select signals |
| 7 | $\overline{\text{LCS0}}$ | O | |
| 8 | $\overline{\text{LCS1}}$ | O | |
| 9 | MSEL | I | CPU memory space select signal |
| 10 | INT0 | I | External interrupt request signals |
| 11 | INT15 | I | |
| 12 | D7 | B | Data bus |
| 13 | D6 | B | |
| 14 | D5 | B | |
| 15 | D4 | B | |
| 16 | D3 | B | |
| 17 | D2 | B | |
| 18 | D1 | B | |
| 19 | D0 | B | |
| 20 | V _{DD} | P | Supply pin |
| 21 | V _{SS} | P | Ground connection pin |
| 22 | A23 (PD7) | B | Address bus/General-purpose port D |
| 23 | A22 (PD6) | B | |
| 24 | A21 (PD5) | B | |
| 25 | A20 (PD4) | B | |
| 26 | A19 | O | Address bus |
| 27 | A18 | O | |
| 28 | A17 | O | |
| 29 | A16 | O | |
| 30 | $\phi 2$ | O | ICE system clock |
| 31 | $\overline{\text{RES}}$ | O | ICE reset signal |
| 32 | R/W | I | ICE read/write signal |
| 33 | $\overline{\text{IRQ}}$ | O | ICE interrupt request signal |
| 34 | $\overline{\text{VP}}$ | I | ICE vector address signal |
| 35 | RDY | O | ICE ready signal |
| 36 | BE | O | ICE bus enable signal |
| 37 | VPA | I | ICE valid program address signal |
| 38 | VDA | I | ICE valid data address signal |
| 39 | $\overline{\text{NMI}}$ | I | Non-maskable interrupt request signal |
| 40 | V _{DD} | P | Supply pin |
| 41 | V _{SS} | P | Ground connection pin |
| 42 | A15 | O | Address bus |
| 43 | A14 | O | |
| 44 | A13 | O | |
| 45 | A12 | O | |
| 46 | A11 | O | |
| 47 | A10 | O | |
| 48 | A9 | O | |
| 49 | A8 | O | |

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| Number | Name | IO ¹ | Description |
|--------|-----------------|-----------------|---|
| 50 | PA7 | B | General-purpose port A |
| 51 | PA6 | B | |
| 52 | PA5 | B | |
| 53 | PA4 | B | |
| 54 | PA3 | B | |
| 55 | PA2 | B | |
| 56 | PA1 | B | |
| 57 | PA0 | B | |
| 58 | ROSC1 | I | RTC crystal oscillator connection pins |
| 59 | ROSC2 | O | |
| 60 | V _{DD} | P | Supply pin |
| 61 | V _{SS} | P | Ground connection pin |
| 62 | A7 | O | Address bus |
| 63 | A6 | O | |
| 64 | A5 | O | |
| 65 | A4 | O | |
| 66 | A3 | O | |
| 67 | A2 | O | |
| 68 | A1 | O | |
| 69 | A0 | O | |
| 70 | EXRDY (PB7) | B | External ready signal/General-purpose port B |
| 71 | PB6 | B | General-purpose port B |
| 72 | PB5 | B | |
| 73 | PB4 | B | |
| 74 | PB3 | B | |
| 75 | PB2 | B | |
| 76 | PB1 | B | |
| 77 | PB0 | B | |
| 78 | CLKIN | I | System clock crystal oscillator connection pins |
| 79 | CLKOUT | O | |
| 80 | V _{DD} | P | Supply pin |
| 81 | V _{SS} | P | Ground connection pin |
| 82 | INT17 (PC7) | B | External interrupt request signals/General-purpose port C |
| 83 | INT16 (PC6) | B | |
| 84 | TCLK1 (PC5) | B | Timer external clock inputs/General-purpose port C |
| 85 | TCLK0 (PC4) | B | |
| 86 | PC3 | B | General-purpose port C |
| 87 | PC2 | B | |
| 88 | PC1 | B | |
| 89 | PC0 | B | |
| 90 | RM3 (PE7) | B | Receive motor phase signals/General-purpose port E |
| 91 | RM2 (PE6) | B | |
| 92 | RM1 (PE5) | B | |
| 93 | RM0 (PE4) | B | |

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| Number | Name | I/O ¹ | Description |
|--------|-----------------|------------------|--|
| 94 | TM3 (PE3) | B | Transmit motor phase signals/General-purpose port E |
| 95 | TM2 (PE2) | B | |
| 96 | TM1 (PE1) | B | |
| 97 | TM0 (PE0) | B | |
| 98 | PDATA (TXD) | O | Thermal head serial output data/Serial I/O transmit data |
| 99 | PCK (SCLK) | B | Thermal head data transmission clock/Serial I/O clock |
| 100 | V _{DD} | P | Supply pin |
| 101 | V _{SS} | P | Ground connection pin |
| 102 | LATCH (RXD) | B | Thermal head data latch signal/Serial I/O receive data |
| 103 | STB3 (PF3) | B | Thermal head strobe signals/General-purpose port F |
| 104 | STB2 (PF2) | B | |
| 105 | STB1 (PF1) | B | |
| 106 | STB0 (PF0) | B | |
| 107 | EXCLK (PF4) | B | Thermal head control external clock/General-purpose port F |
| 108 | HVON | O | Head voltage ON/OFF control signal |
| 109 | PROTECT | I | Head protection abnormality signal input |
| 110 | ID7 | B | Image processor memory data bus |
| 111 | ID6 | B | |
| 112 | ID5 | B | |
| 113 | ID4 | B | |
| 114 | ID3 | B | |
| 115 | ID2 | B | |
| 116 | ID1 | B | |
| 117 | ID0 | B | |
| 118 | ACLK1 | O | Image sensor transmission clocks |
| 119 | ACLK2 | O | |
| 120 | V _{DD} | P | Supply pin |
| 121 | V _{SS} | P | Ground connection pin |
| 122 | AVDD | P | Analog supply pin |
| 123 | AIN | I | Analog image signal input |
| 124 | TEMP | I | Thermistor input |
| 125 | ATAP | I | Built-in A/D converter reference voltage |
| 126 | AVSS | P | Analog ground connection |
| 127 | RESET | I | Reset signal |
| 128 | SH | O | Image sensor start pulse |
| 129 | RS | O | Image sensor reset pulse |
| 130 | ASAMP | O | Built-in A/D converter sampling point monitor signal |
| 131 | IRD | O | Image processor memory read signal |
| 132 | IWR | O | Image processor memory write signal |

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| Number | Name | IO ¹ | Description |
|--------|-----------------|-----------------|--|
| 133 | IA13 | O | Image processor memory address bus |
| 134 | IA12 | O | |
| 135 | IA11 | O | |
| 136 | IA10 | O | |
| 137 | IA9 | O | |
| 138 | IA8 | O | |
| 139 | IA7 | O | |
| 140 | V _{DD} | P | Supply pin |
| 141 | V _{SS} | P | Ground connection pin |
| 142 | RAS (PF5) | B | DRAM address strobes/General-purpose port F |
| 143 | CAS (PF6) | B | |
| 144 | IA6 | O | Image processor memory address bus |
| 145 | IA5 | O | |
| 146 | IA4 | O | |
| 147 | IA3 | O | |
| 148 | IA2 | O | |
| 149 | IA1 | O | |
| 150 | IA0 | O | |
| 151 | ICS | O | Image processor memory chip select |
| 152 | ICLK (PD3) | B | Image processor external clock/General-purpose port D |
| 153 | SPCLK (PD2) | B | Speaker clock output/General-purpose port D |
| 154 | BACK (PD1) | B | External master device bus acknowledge signal/General-purpose port D |
| 155 | BREQ (PD0) | B | External master device bus request signal/General-purpose port D |
| 156 | TEST1 | I | Test pins |
| 157 | TEST0 | I | |
| 158 | BACKUP | I | Power-down signal |
| 159 | EMU | I | ICE monitor in-operation signal |
| 160 | V _{DD} | P | Supply pin |

1. I = input, B = bidirectional, O = output, P = power

Specifications

Absolute Maximum Ratings at V_{SS} = 0V

| Parameter | Symbol | Conditions | Rating | Unit |
|-----------------------------|---------------------------------|------------------------|-------------------------------|------|
| Maximum supply voltage | V _{DD} max | T _a = 25°C | -0.3 to +7.0 | V |
| Input/output voltage | V _I , V _O | T _a = 25°C | -0.3 to V _{DD} + 0.3 | V |
| Allowable power dissipation | P _d max | T _a ≤ 70°C | 600 | mW |
| Operating temperature | T _{opr} | | -30 to +70 | °C |
| Storage temperature | T _{stg} | | -55 to +125 | °C |
| Soldering temperature | T _{sol} | Manual soldering (3s) | 350 | °C |
| | | Reflow soldering (10s) | 235 | °C |

Allowable Operating Ranges at T_a = -30 to +70°C, V_{SS} = 0V

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|----------------|-----------------|------------|-----|-----|-----------------|------|
| Supply voltage | V _{DD} | | 4.5 | - | 5.5 | V |
| Input voltage | V _{IN} | | 0 | - | V _{DD} | V |

DC Characteristics at $T_a = -30$ to $+70^\circ\text{C}$, $V_{DD} = 4.5$ to 5.5V

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---------------------------|------------|--|------|--------|------|---------------|
| Input high-level voltage | V_{IH1} | All inputs except PCK (SCLK) | 2.2 | - | - | V |
| Input low-level voltage | V_{IL1} | All inputs except PCK (SCLK) | - | - | 0.8 | V |
| Input high-level voltage | V_{IH2} | PCK (SCLK), Schmitt trigger input | 2.5 | - | - | V |
| Input low-level voltage | V_{IL2} | PCK (SCLK), Schmitt trigger input | - | - | 0.6 | V |
| Input leakage current | I_L | | -25 | - | +25 | μA |
| Output high-level voltage | V_{OH} | $I_{OH} = -3\text{mA}$ | 2.4 | - | - | V |
| Output low-level voltage | V_{OL} | $I_{OL} = 3\text{mA}$ | - | - | 0.4 | V |
| Output leakage current | I_{OZ} | High-impedance output | -100 | - | +100 | μA |
| Oscillator frequency | f_{CLK1} | CLKIN, CLKOUT | - | - | 16 | MHz |
| | f_{CLK2} | ICLK, TCLK0, TCLK1 | - | - | 16 | MHz |
| | f_{CLK3} | ROSC1, ROSC2 | - | 32.768 | - | kHz |
| Current dissipation | I_{DD1} | Operating normally | - | 50 | 90 | mA |
| | I_{DD2} | Power-down, $V_{DD} = 2\text{V}$, BACKUP = LOW | - | 3 | 5 | μA |

Function Outline**CPU Peripheral Circuits**

- Generates 80-series CPU compatible CS/RD/WR signals
- Chip select signal outputs for program ROM, SRAM and I/O device connections
- ROM, SRAM and DRAM sizes settable in 64KB units
- Inserts wait cycles when accessing ROM, SRAM and I/O
- Internal/external DMA controller bus arbitration function

Image Processor

- Number of processed picture elements (pels)
 - 2048 pels/line (uses 64K memory, with black and white correction)
 - 4096 pels/line (uses 64K memory, with white correction only)
 - 4096 pels/line (uses 256K memory, with black and white correction)
- 500ns/pel max. processing rate
- 1 external, medium-speed memory
 - 100ns access time at 500ns/pel rate
- Various kinds of clocks
 - Internal clock mode, with 1, 1/2, 1/4, 1/8 frequency division capability
 - External clock mode, with optional external clock input capability
- AGC, 8-bit A/D converter built-in (with delay adjust function)
- Thermal printer head temperature monitor function
- Sensor drive circuit (CCD, various CIS types)
- Digital clamp (dot clamp, even-odd clamp)
- Distortion correction (white, black, all pels)

- γ correction (user-definable curve)
- Simple two-value processing (fixed threshold value, density-adjusted threshold value)
- Half-tone processing
 - Systematic dither method (64 gradations), dither threshold value adjustable
 - Error diffusion method (64 gradations)
- Image reduction (thinning out, black fine line hold, white fine line hold)

Codec Accelerator

- Image data dot change detection, run-length or line start absolute address output
- Run-length image data coding
- Maximum 4K run-length processing
- Image data DMA transmission capability

TPH Interface

- 4MHz, 2MHz, 1MHz and 500kHz transmission clock frequency
- Switchable rising-edge/falling-edge clock phase
- Strobe division: 1, 2, and 4
- Strobe width: 32 μs to 8.16ms
- Switchable strobe and latch pulse polarity
- Strobe and latch pulse can be generated manually and treated as a general-purpose output port
- Head supply ON/OFF control
- Head protection input pin (PROTECT) setup
 - Mode 1: HVON and STB0 to STB3 are set to inactive state after a continuous low-level input of approximately 64 ms
 - Mode 2: HVON and STB0 to STB3 are set to inactive state immediately after a low-level signal input.

Motor Interface

- Transmit/receive 2-channel stepping motor interface
- 4-phase motor (excitation method: 1 phase/2 phases/1-2 phases)
- Forward/reverse-selectable control register
- Motor output polarity selectable
- 2 phase change triggers (register-selectable) for both transmit and receive
 - Transmit motor trigger
 - Phase change by register bit ON/OFF
 - Phase change by image processor-controlled motor phase advance trigger
 - Receive motor trigger
 - Phase change by register bit ON/OFF
 - Phase change by timer 3 output

DMA Controller

- 3-channel transmission, memory ↔ I/O
 - Channel 0: Image processor → memory
 - Channel 1: Codec accelerator ↔ memory
 - Channel 2: Memory → TPH interface
- Channel 2 supporting a latchless head
- 16MB addresses/64K transfer count
- 2.6MB/s max. transfer speed
- Individual DMA request permit/prohibit
- Auto-initialization function
- Fixed precedence order: channel 0 > channel 1 > channel 2

Timer

- 6 independent 16-bit counters on-chip
- 8-bit prescaler on-chip for each counter
- 244Hz to 15.6kHz speaker clock generator
- External clock inputs selectable for timer 0 and timer 1

DRAM Controller

- 256K/1M/4Mb DRAM support, up to 120ns access time supported
- CAS-before-RAS refresh
- Employs early-write mode
- Internal refresh counter: 4ms refresh time for 256K, 8ms for 1M, 16ms for 4M
- Register setting capability for 9 dummy refresh cycle execution

Interrupt Controller

- 18-level interrupt control (internal: 14 levels, external: 4 levels)
- Individual level mask processing
- Interrupt vector address output

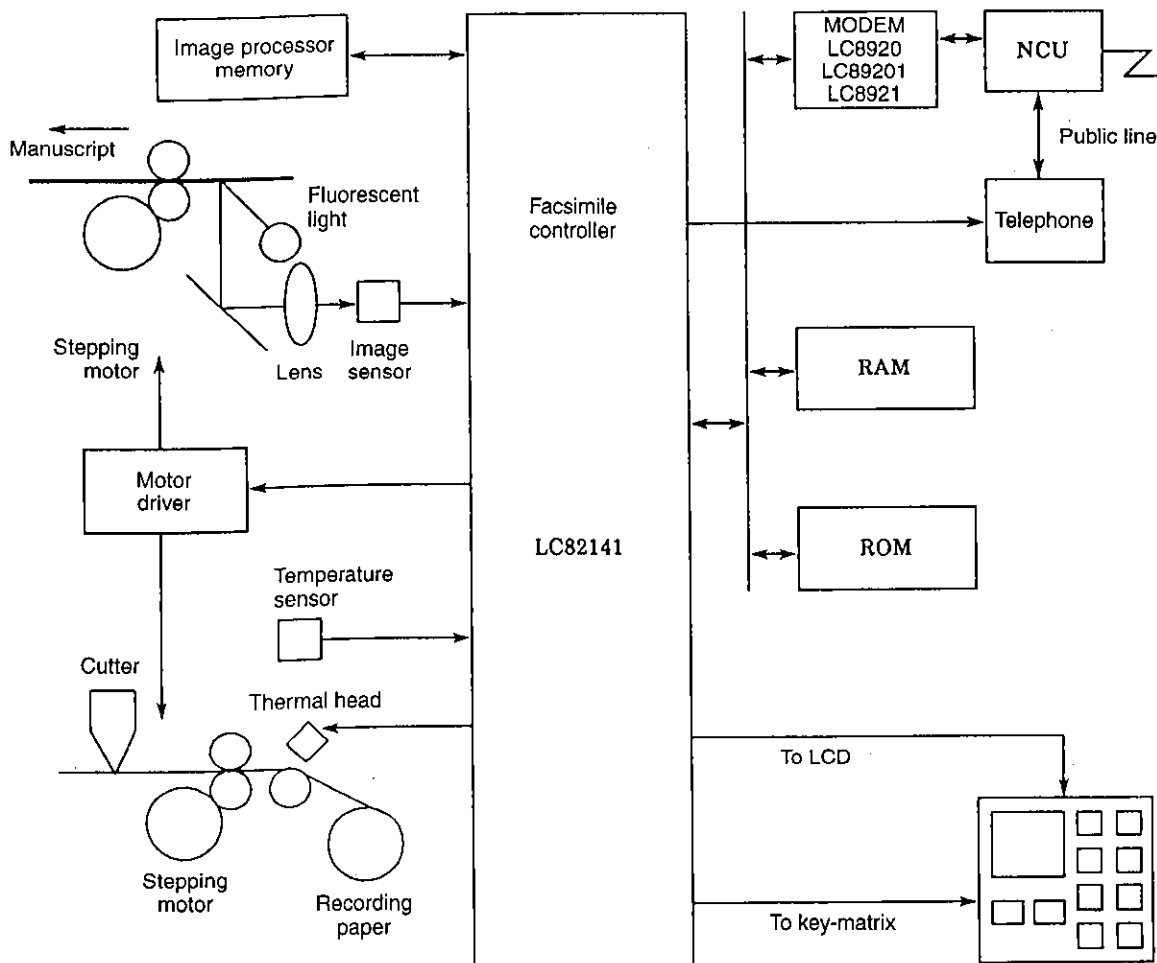
RTC

- Time function with alarm
- 100-year calendar
- 12-hour/24-hour time display, summer time set capability
- Leap year, short/long month auto-correction
- Selectable binary or BCD data for time, calendar and alarm
- 3 types of interrupts
 - Alarm interrupt
 - Periodic interrupt
 - Update ended interrupt

General-Purpose Ports

- 20 to 32 input/output ports
- Each port can be configured as an input or output
- Extendable up to 47 ports by switchover to dedicated pins

Sample Application Circuit



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